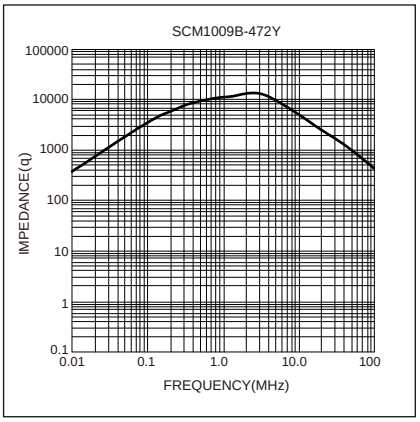
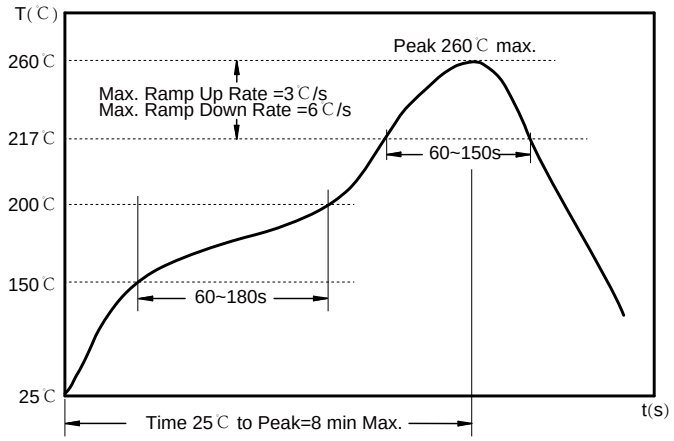

1
2
4
3
10.5 max.

Electrical Properties:

# Typical Electrical Characteristics:



## Soldering Reflow:




Preheat condition: 150 ~200℃/ 60~180 sec.

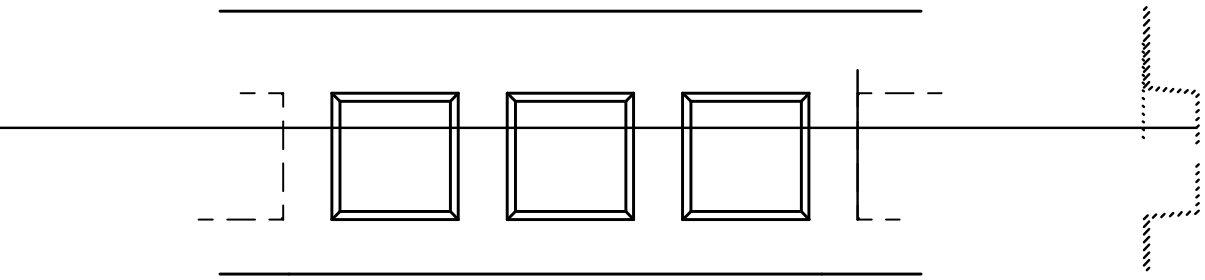
Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

Max time at max temperature: 10 sec.

## Packaging Information:

### Tape Dimension:

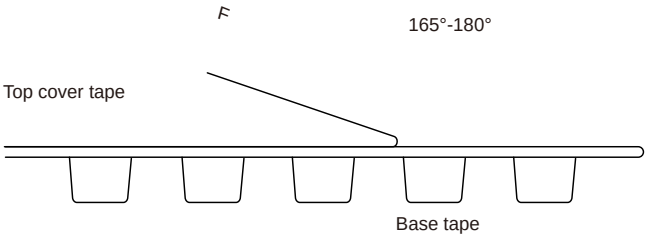


| Series | A0 (mm) | B0 (mm) | D (mm) | P0 (mm) | P1 (mm) | W (mm) | K0 (mm) | E (mm) | T (mm) |
|---|---|---|---|---|---|---|---|---|---|
| 1009 | 9.4 ± 0.1 | 10.8 ± 0.1 | 1.5 ± 0.1 | 4.0 ± 0.1 | 12.0 ± 0.1 | 24.0 ± 0.3 | 6.4 ± 0.1 | 1.75 ± 0.1 | 0.50 ± 0.05 |

### Product Marking:

| | |
|---|---|
| Marking | Dot+Printing Inductance) |

Peel force of top cover tape:




Reel Dimension Embossed Carrier [mm]



Packaging Quantity:

# Cautions and Warnings:

## Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35ÁC, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

## Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.

## Conformal coating:

- The inductance value may change due to the high cure stress of the resin used for coating or molding.
- An open circuit may occur due to mechanical stress from the resin, its amount, cured shape, or operating conditions.
- Please exercise careful attention when selecting a resin for the coating or molding process.
- Prior to using the coating resin, please verify that no reliability issues are observed.
- When applying conformal coating for product protection, materials with a high shrinkage rate should be avoided.If such materials must be used, it is recommended to apply silicone around the inductor core in a closed loop to prevent the conformal coating from flowing into or penetrating the windings, thereby avoiding open-circuit failures caused by the coating's thermal stress.